



C SUN

志聖法人說明會

Investor Conference

Morrison Liang, Chairman

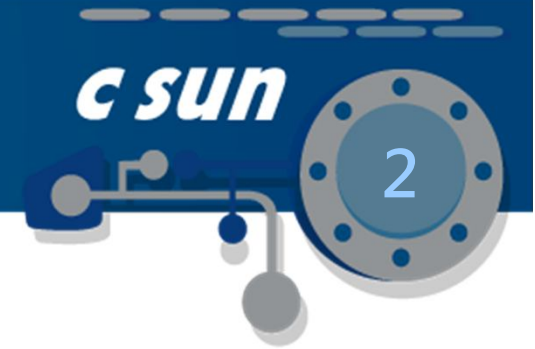
Dr. Toshio Huang, Executive Vice President of FPD Business Unit

Steven Lai, Executive Vice President of PCB Business Unit

Place: Taiwan Stock Exchange Corporation

October 30th, 2018

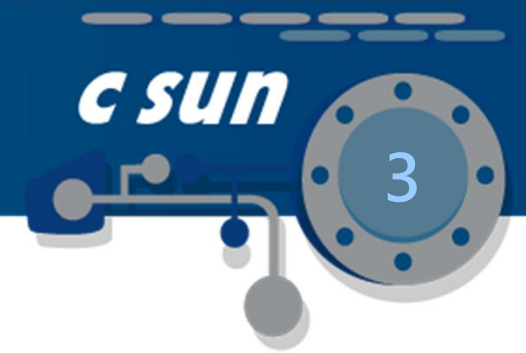
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Manufacturing Plant



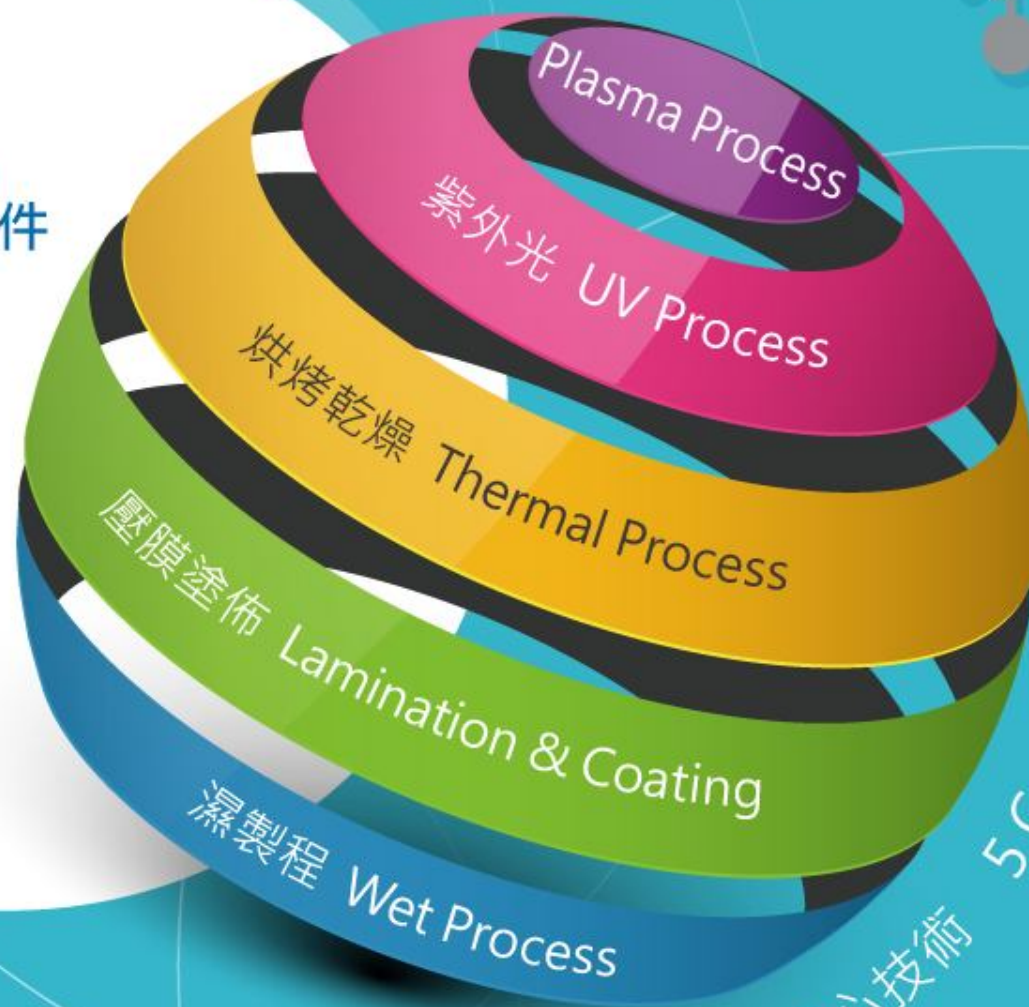
Core Tech

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專利
認證 **310** 件

發明
件數 **69** 件



五大核心技術 5 Core Technologies

7 Habits

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5

他人之得，不必為自己之失
大家都可以是贏家

Think Win-Win
雙贏思維

了解彼此需求，
做有效溝通的聆聽者
**Seek First to Understand,
then to be Understood**

知彼解己

尊重差異，整合不同觀點
共創最佳的合作解決方法

Synergize
統合綜效

不斷學習、持續進步
身心平衡發展

Sharpen the Saw
不斷更新

The 7 Habits of Highly Effective People

主動創造，
打破障礙與限制

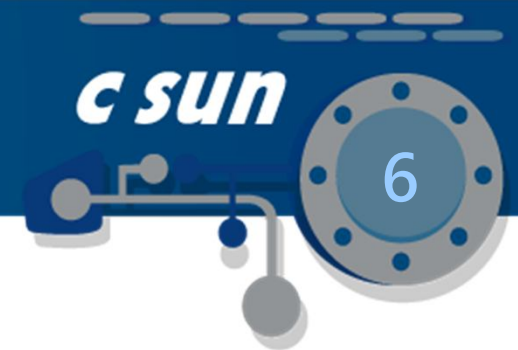
Be Proactive
主動積極

確立目標
克服困難徹底執行
**Begin with the End
in Mind** 以終為始

訂定優先順序，
在關鍵任務與瑣碎事物中
追求平衡

First Things First
要事第一

Agenda



➤ 2018Q3 營運成果

➤ 市場機會與產品發展

- Flat Panel Display (FPD)
- Advanced Packaging(SEMI)
- Printed Circuit Board(PCB)
- 子公司 創峰

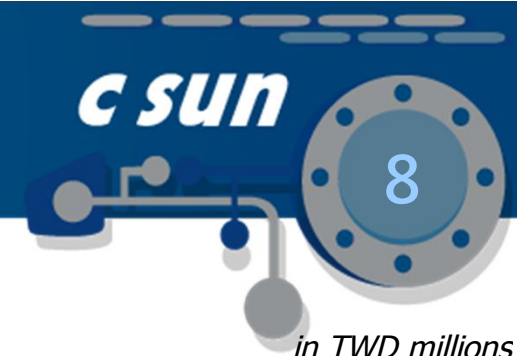
➤ Q&A

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2018 Q3 Operating Results



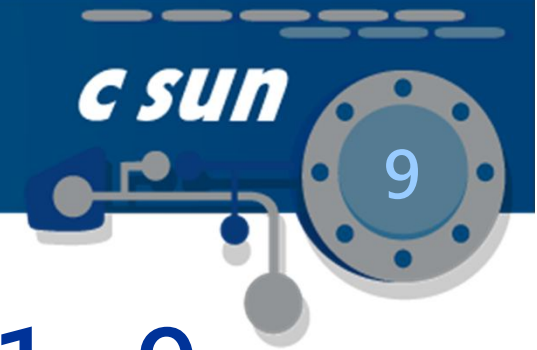
2018Q3 Operating Results



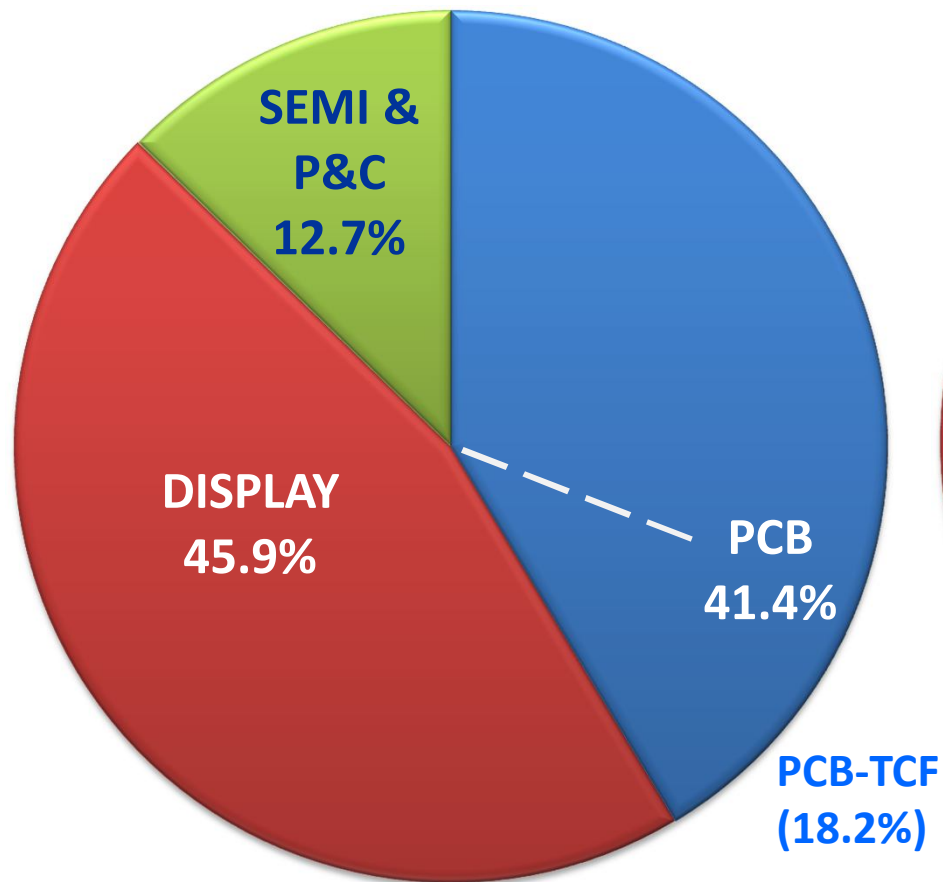
	2018Q3*		2017Q3		2017		2016		2015	
	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	4,213		3,669		5,003		3,885		3,363	
COGS			2,414	65.8%	3,345	66.9%	2,722	70.1%	2,619	77.9%
Gross Margin			1,255	34.2%	1,658	33.1%	1,162	29.9%	744	22.1%
Operating Expense			825	22.5%	1,091	21.8%	951	24.5%	968	28.8%
Operating Income			430	11.7%	567	11.3%	212	5.5%	(224)	-6.7%
Net Non-Op. Profit			(45)	-1.2%	(53)	-1.1%	(10)	-0.3%	(419)	-12.4%
Net Income before tax			385	10.5%	514	10.3%	202	5.2%	(643)	-19.1%
Net Income after tax			320	8.7%	427	8.5%	200	5.1%	(730)	-21.7%
Attribute to stockholder's of the parent	399	9.5%	302	8.2%	403	8.1%	210	5.4%	(496)	-14.7%
ROE	17.09%		13.94%		18.20%		10.16%		-19.55%	
EPS (NT\$/after tax)	\$2.67		\$2.02		\$2.70		\$1.39		(\$3.12)	
Debt Ratio			61.36%		59.81%		62.17%		62.69%	

Note : * unaudited

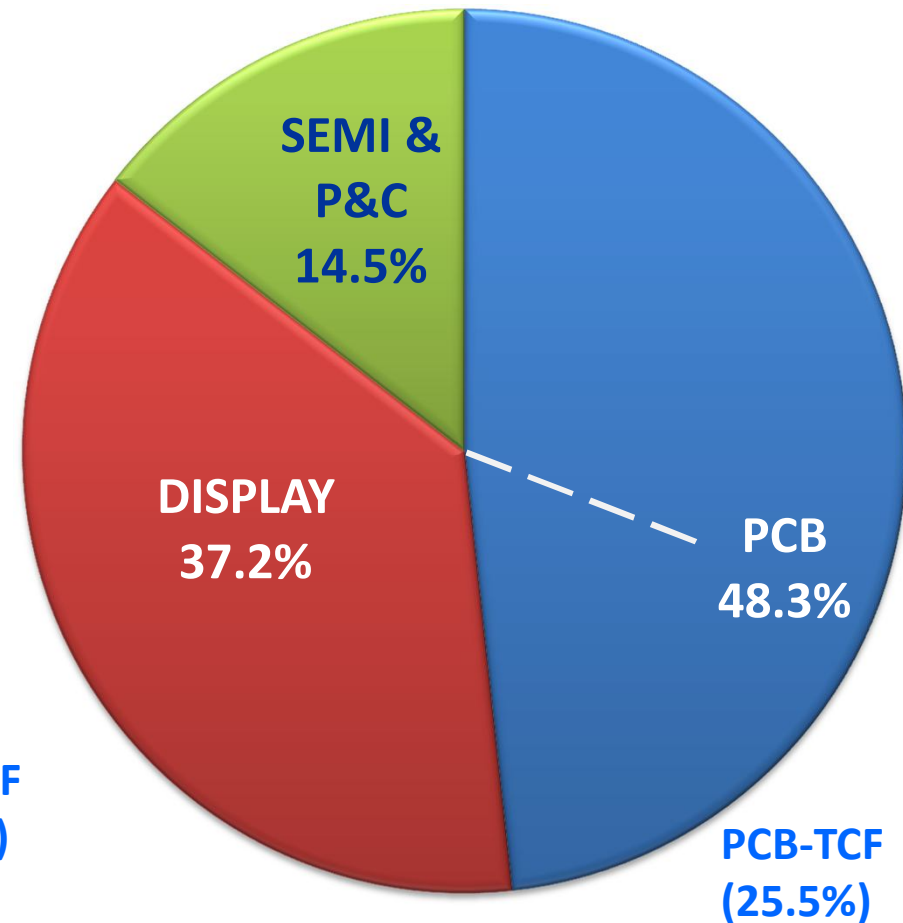
Revenue Breakdown



2017

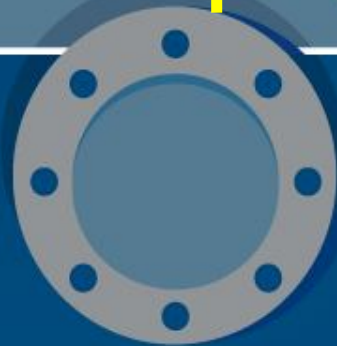
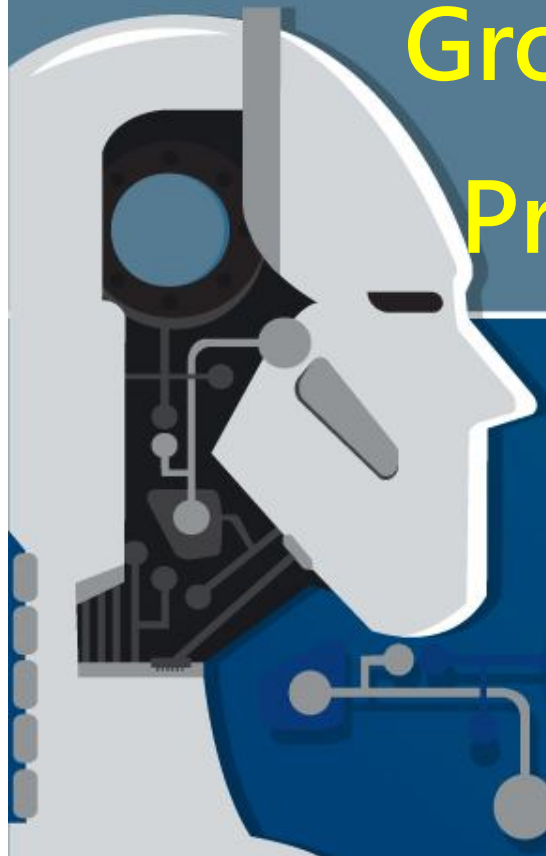


2018/1~9



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Growth Opportunities & Product Development



Core Techs in SEMI/FPD UV & Thermal

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真空/自動化
OVEN(SEMI)



熱風 for TFT



UV2 for TFT



熱板 for TFT

FPD BU

G8.6 & G11 market share expanded

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➤ G8.6/G11設備擴產多，現有客戶與未來擴廠

SDP

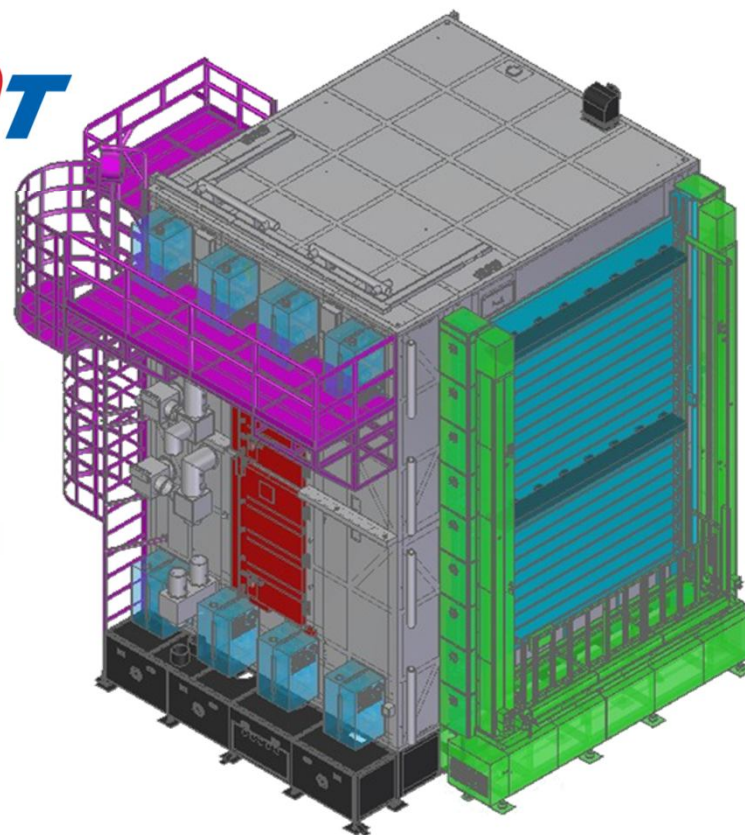
超视界国际科技（广州）有限公司

CEC
中国电子

CHOT



HKC



FPD BU

Automotive Display

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- 車載顯示面板，網印後自動化乾燥生產線，開發完成導入量產線。



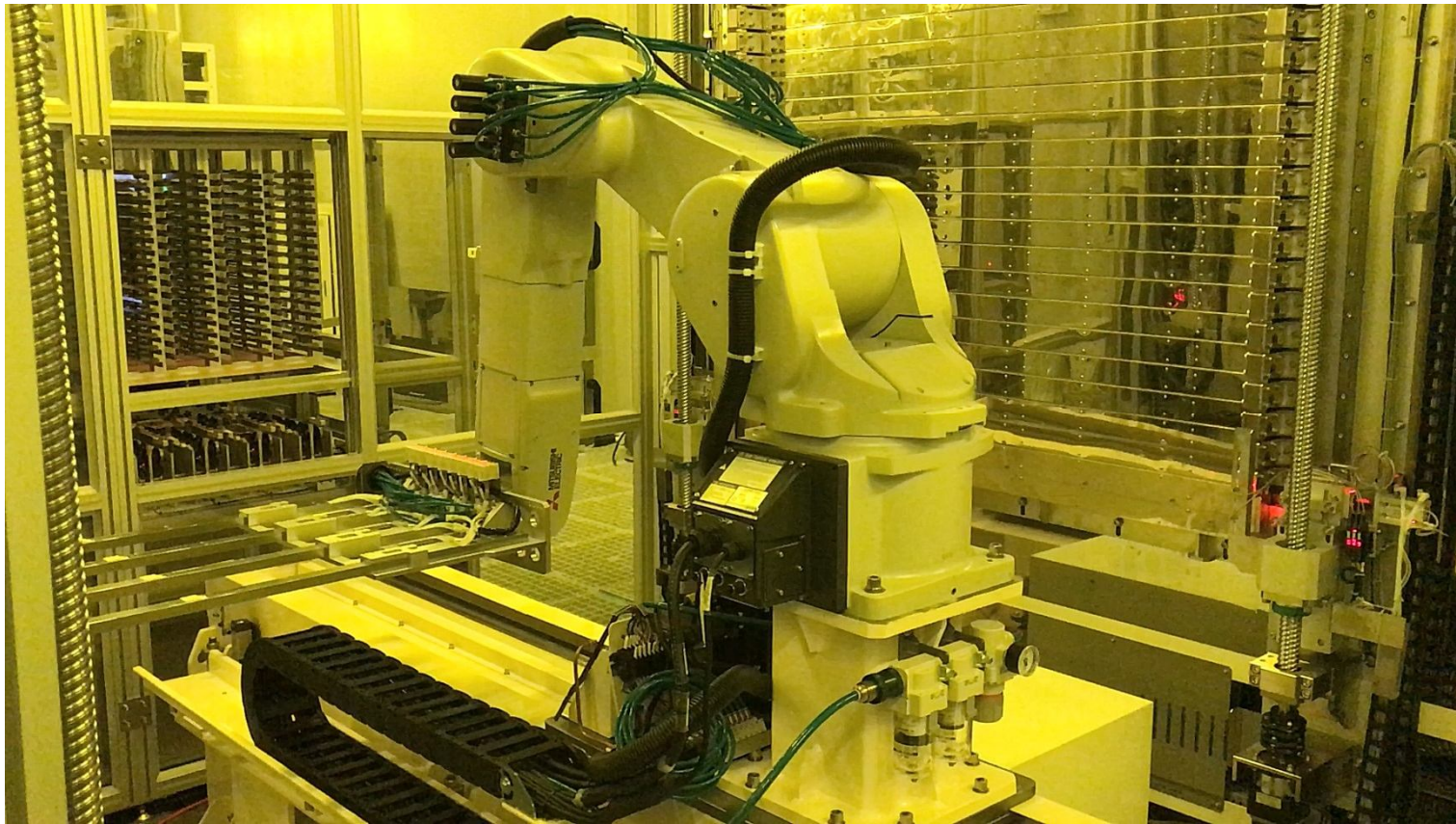
FPD BU

Thermal Process

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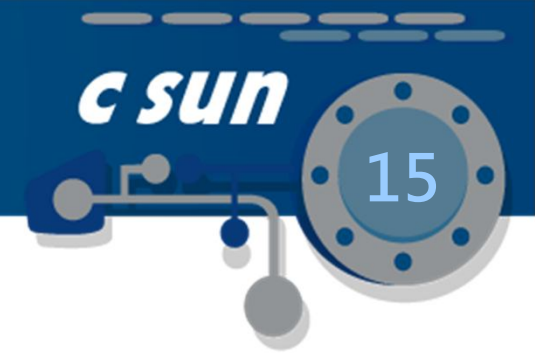
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- 3D玻璃機殼防破碎製程已導入志聖生產設備

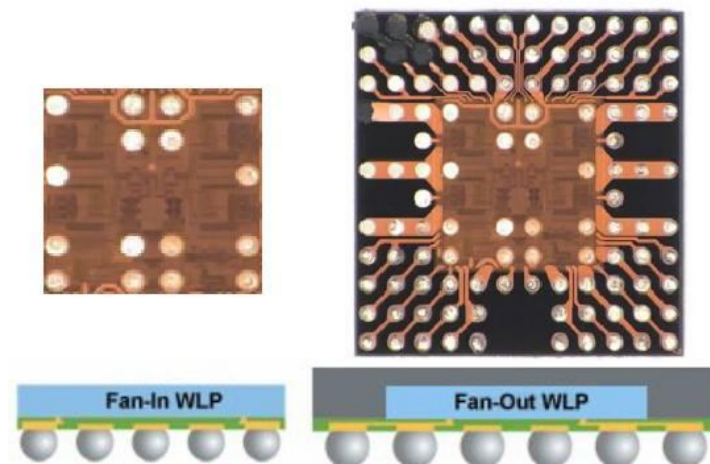


FPD BU

The Development of Semiconductor Advanced Packaging



- 先進封裝製程發展快速(Fan-Out)，封裝載具變化(WLP、PLP)。
- 熱技術應用與現況:
 - 先進封裝Molding段:與外商合作切入Molding 固化製程。
 - 與客戶合作開發切入PLP RDL 全自動烘烤設備，製程驗證中
 - 傳統Oven結合自動化技術，導入客戶端
- 中國開始發展先進封裝製程，設備需求啟動

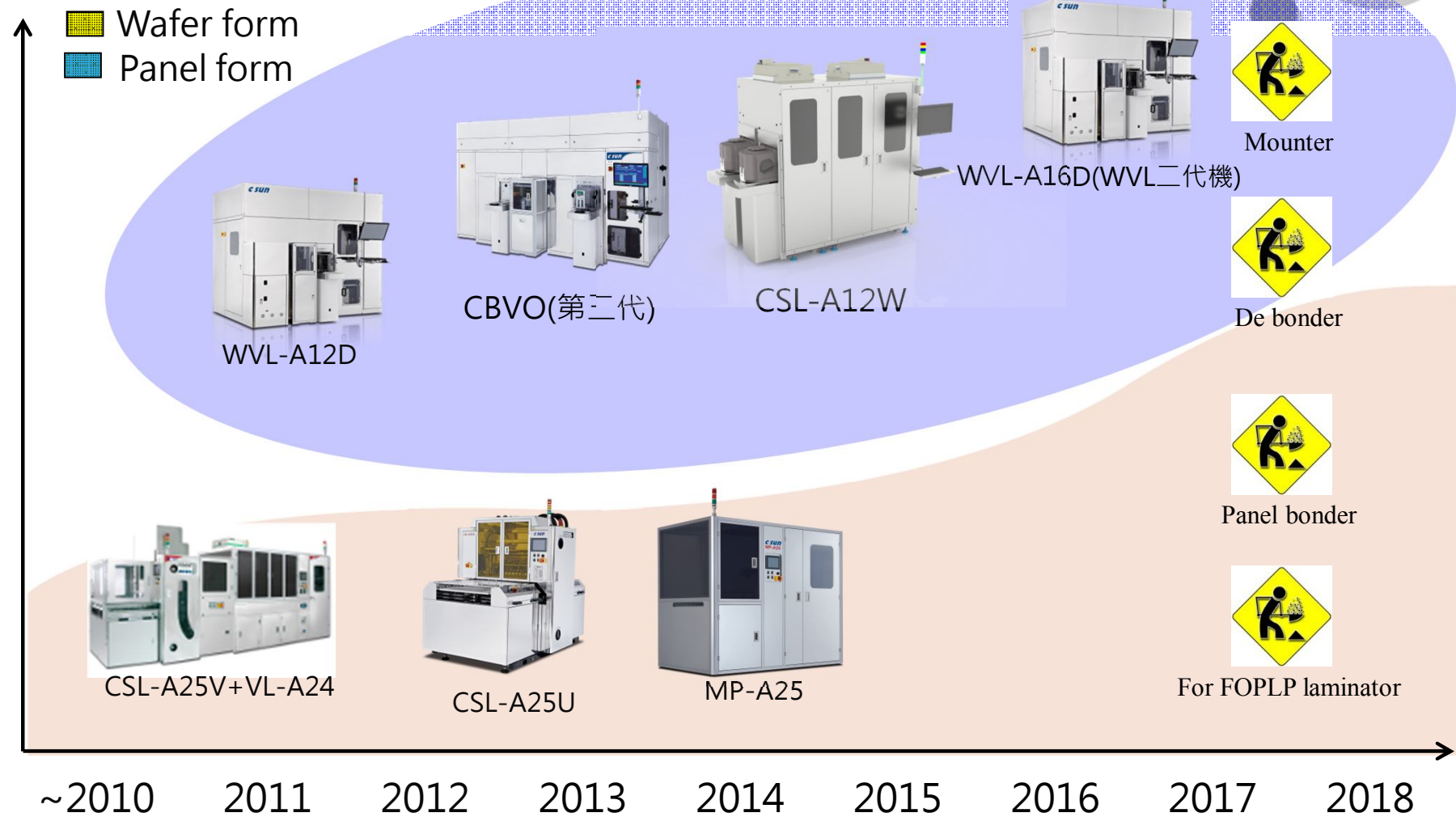


FPD BU

Product Development in Semiconductor Field

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PCB BU

Trailing the development of semiconductor advanced packaging

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- 高階AI先進封裝製程
- 消費性晶片先進封裝製程



PCB BU

Lamination Exposure & Smart Production System in PCB/SEMI/PV

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應用於：PCB、半導體、太陽能



PCB BU

Exposure Product Roadmap

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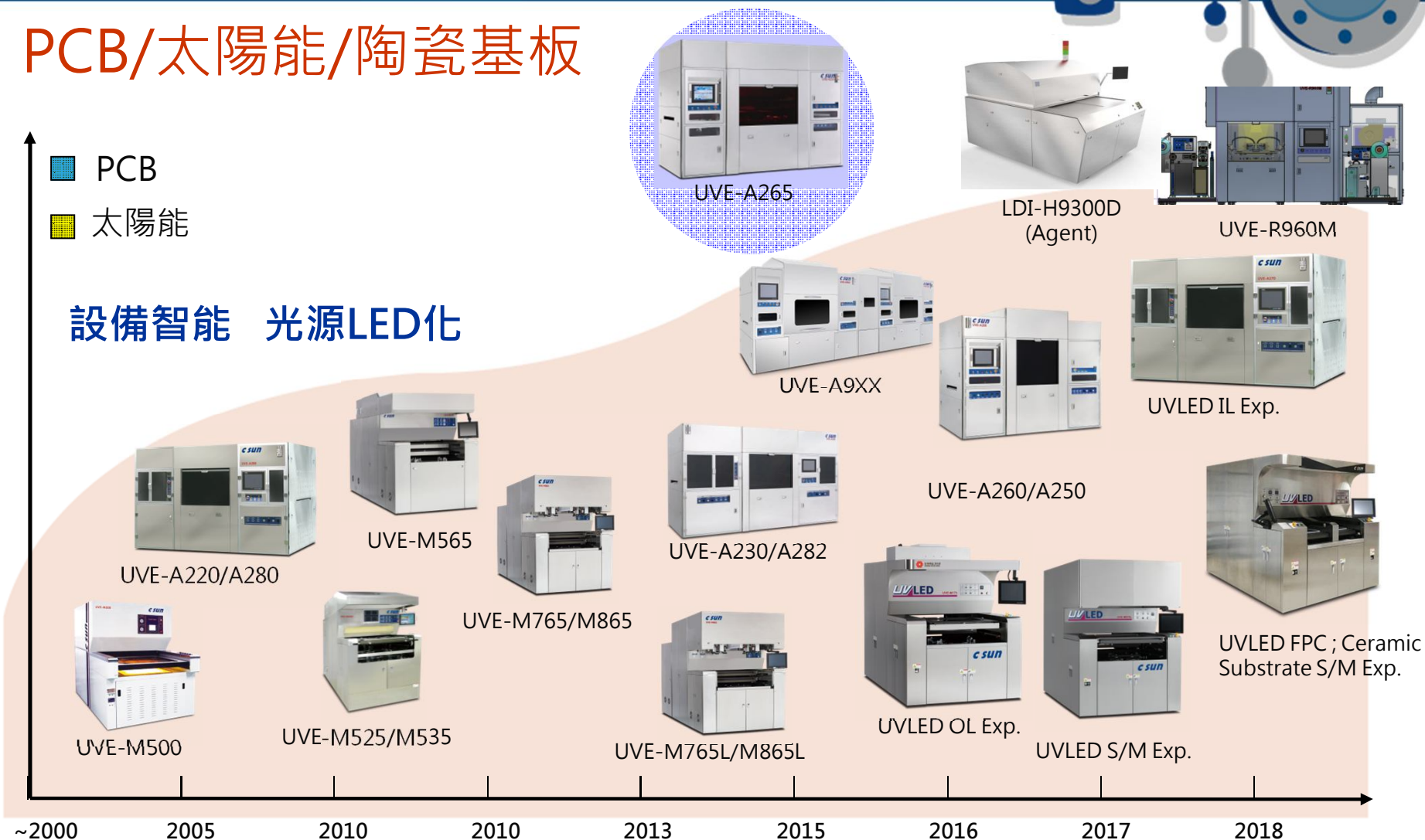
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PCB/太陽能/陶瓷基板

■ PCB

■ 太陽能

設備智能 光源LED化



PCB BU

Lamination Product Roadmap

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PCB/太陽能/陶瓷基板

■ PCB

■ 太陽能

設備智能 跨產業應用



RC-A24



CSL-A25V+VL-A24



MP-A25



PL-A24



CSL-A25



CSL-A32



CSL-A25PHII



CSL-A25UII



RTR-500PH

~1996

2000

2004

2009

2010

2014

2016

2017

2018

PCB BU

Intelligent System Service Scenario

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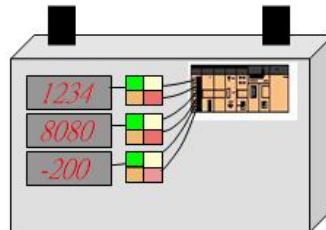
現在(As-Is)

設備這麼多，人力永遠不夠



透過定期檢點管理表定期檢驗，零件異常而停機時，進行替換零件。

機台狀態數值異常，不知道哪個元件出錯。



機台狀態顯示畫面



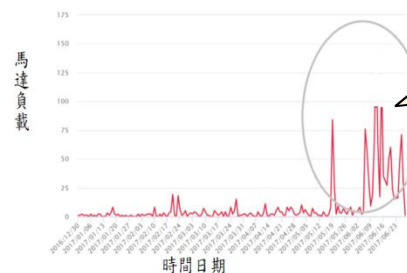
曝光光源均勻度量測：
1天3班，每個班都要量1次30分鐘，好浪費時間，有時數據隨便寫，反正主管也不知道。

底片對位設定(μm)	
對位移動量	3
底片精度	50
初對位設定(μm)	
對位移動量	10
真空檢測設定(μm)	
對位移動量	999
D精度	999
底片精度	999

有時候操作員為了提高產能擅自修改機台設定值，又產生好多報廢。

未來(To-Be)

智能化預測維護與監控

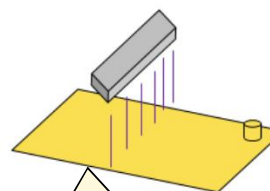


實時監測馬達負載，即將發生異常，即時通知工務趁待料時檢修，僅停機4小時且不影響產能。

區域B感測器3號Cable發生斷線，請確認連接器配線。



通訊



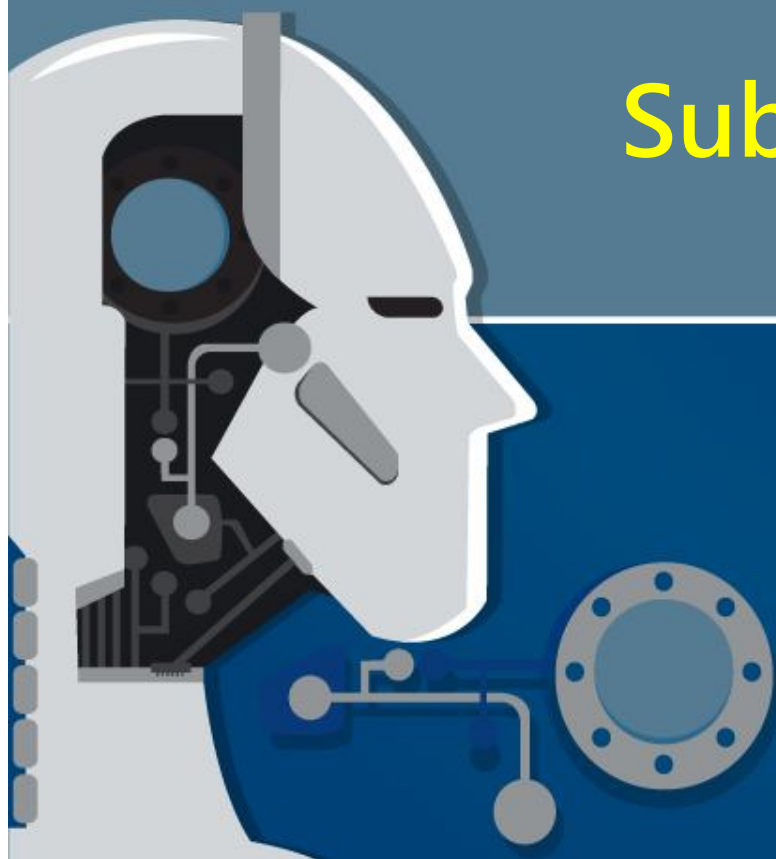
智慧型自動偵測光源功能，一鍵執行，數據自動上傳，確保製程穩定，也不用在人工抄寫數據。



料號重要參數統一由上位系統下達，有效避免報廢。

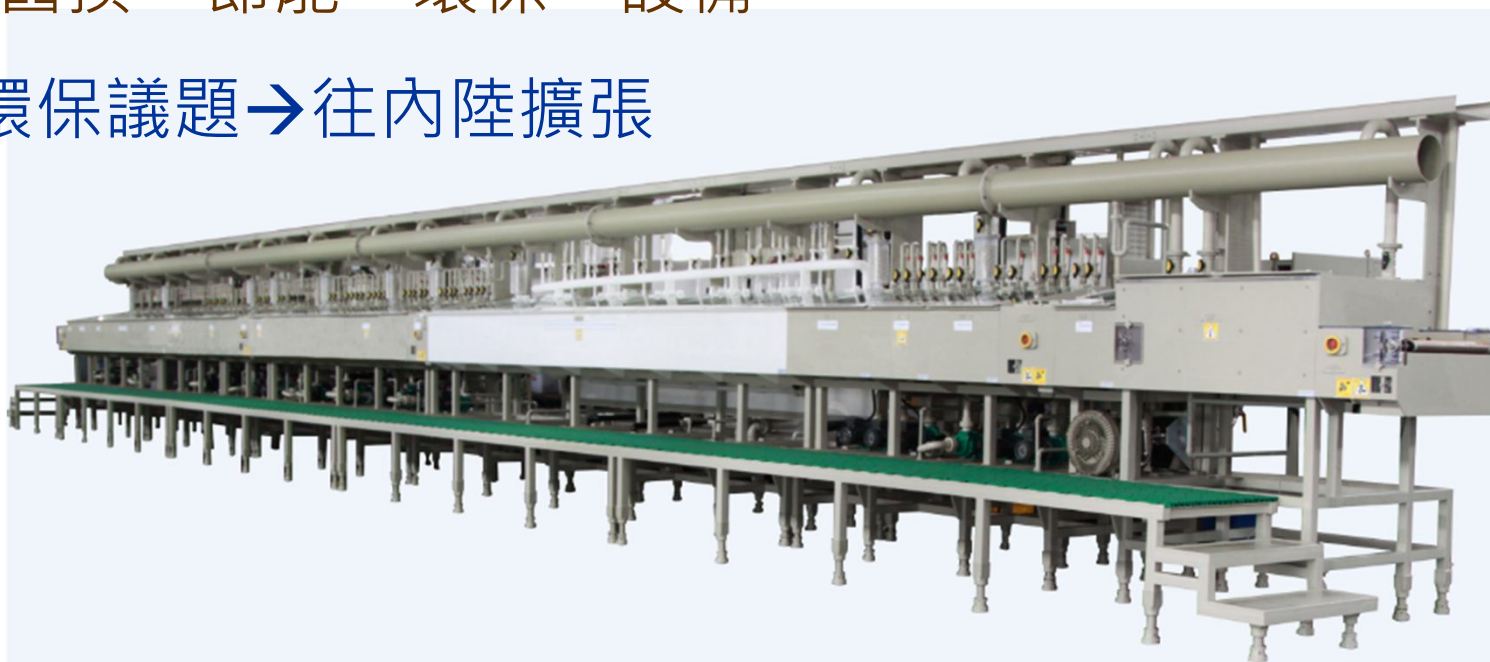
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Subsidiary-TCF



2018營收成長動能

- Desmear PTH取代既有龍門線設備
 - 耗能、耗水、耗藥水
 - 汰舊換“節能、環保”設備
- 沿海環保議題→往內陸擴張





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Thank You